

Small Signal MOSFET

115 mAmps, 60 Volts

N-Channel SOT-23

- Pb-Free Package is Available.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	60	Vdc
Drain-Gate Voltage ($R_{GS} = 1.0 \text{ M}\Omega$)	V_{DGR}	60	Vdc
Drain Current – Continuous $T_C = 25^\circ\text{C}$ (Note 1.) $T_C = 100^\circ\text{C}$ (Note 1.) – Pulsed (Note 2.)	I_D I_D I_{DM}	± 115 ± 75 ± 800	mAdc
Gate-Source Voltage – Continuous – Non-repetitive ($t_p \leq 50 \mu\text{s}$)	V_{GS} V_{GSM}	± 20 ± 40	Vdc Vpk

THERMAL CHARACTERISTICS

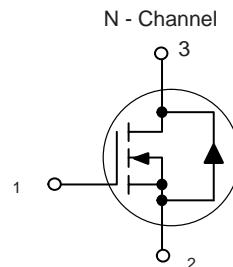
Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 3.) $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	225 1.8	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	556	$^\circ\text{C}/\text{W}$
Total Device Dissipation Alumina Substrate, (Note 4.) $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	300 2.4	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	417	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

- The Power Dissipation of the package may result in a lower continuous drain current.
- Pulse Test: Pulse Width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 2.0\%$.
- FR-5 = $1.0 \times 0.75 \times 0.062$ in.
- Alumina = $0.4 \times 0.3 \times 0.025$ in 99.5% alumina.

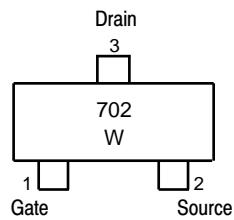
L2N7002LT1



115 mAmps
60 VOLTS
 $R_{DS(on)} = 7.5 \Omega$



MARKING DIAGRAM & PIN ASSIGNMENT



702 = Device Code
W = Work Week

ORDERING INFORMATION

Device	Marking	Shipping
L2N7002LT1	702	3000 Tape & Reel
L2N7002LT1G	702(Pb-Free)	3000 Tape & Reel

L2N7002LT1

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Drain–Source Breakdown Voltage ($V_{GS} = 0$, $I_D = 10 \mu\text{Adc}$)	$V_{(BR)DSS}$	60	—	—	Vdc
Zero Gate Voltage Drain Current ($V_{GS} = 0$, $V_{DS} = 60 \text{ Vdc}$)	I_{DSS}	—	—	1.0 500	μAdc
Gate–Body Leakage Current, Forward ($V_{GS} = 20 \text{ Vdc}$)	I_{GSSF}	—	—	100	nAdc
Gate–Body Leakage Current, Reverse ($V_{GS} = -20 \text{ Vdc}$)	I_{GSSR}	—	—	-100	nAdc

ON CHARACTERISTICS (Note 2.)

Gate Threshold Voltage ($V_{DS} = V_{GS}$, $I_D = 250 \mu\text{Adc}$)	$V_{GS(\text{th})}$	1.0	1.6	2.5	Vdc
On–State Drain Current ($V_{DS} \geq 2.0 \text{ V}_{DS(\text{on})}$, $V_{GS} = 10 \text{ Vdc}$)	$I_{D(\text{on})}$	500	—	—	mA
Static Drain–Source On–State Voltage ($V_{GS} = 10 \text{ Vdc}$, $I_D = 500 \text{ mAdc}$) ($V_{GS} = 5.0 \text{ Vdc}$, $I_D = 50 \text{ mAdc}$)	$V_{DS(\text{on})}$	— —	— —	3.75 0.375	Vdc
Static Drain–Source On–State Resistance ($V_{GS} = 10 \text{ V}$, $I_D = 500 \text{ mAdc}$)	$r_{DS(\text{on})}$	—	1.4	7.5	Ohms
$T_C = 25^\circ\text{C}$ $T_C = 125^\circ\text{C}$ $(V_{GS} = 5.0 \text{ Vdc}$, $I_D = 50 \text{ mAdc}$)	$T_C = 25^\circ\text{C}$ $T_C = 125^\circ\text{C}$	—	—	13.5	
		—	1.8	7.5	
Forward Transconductance ($V_{DS} \geq 2.0 \text{ V}_{DS(\text{on})}$, $I_D = 200 \text{ mAdc}$)	g_{FS}	80	—	—	mmhos

DYNAMIC CHARACTERISTICS

Input Capacitance ($V_{DS} = 25 \text{ Vdc}$, $V_{GS} = 0$, $f = 1.0 \text{ MHz}$)	C_{iss}	—	17	50	pF
Output Capacitance ($V_{DS} = 25 \text{ Vdc}$, $V_{GS} = 0$, $f = 1.0 \text{ MHz}$)	C_{oss}	—	10	25	pF
Reverse Transfer Capacitance ($V_{DS} = 25 \text{ Vdc}$, $V_{GS} = 0$, $f = 1.0 \text{ MHz}$)	C_{rss}	—	2.5	5.0	pF

SWITCHING CHARACTERISTICS (Note 2.)

Turn-On Delay Time	$(V_{DD} = 25 \text{ Vdc}$, $I_D \cong 500 \text{ mAdc}$,	$t_{d(\text{on})}$	—	7	20	ns
Turn-Off Delay Time	$R_G = 25 \Omega$, $R_L = 50 \Omega$, $V_{gen} = 10 \text{ V}$	$t_{d(\text{off})}$	—	11	40	ns

BODY–DRAIN DIODE RATINGS

Diode Forward On–Voltage ($I_S = 11.5 \text{ mAdc}$, $V_{GS} = 0 \text{ V}$)	V_{SD}	—	—	-1.5	Vdc
Source Current Continuous (Body Diode)	I_S	—	—	-115	mAdc
Source Current Pulsed	I_{SM}	—	—	-800	mAdc

2. Pulse Test: Pulse Width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 2.0\%$.

L2N7002LT1

TYPICAL ELECTRICAL CHARACTERISTICS

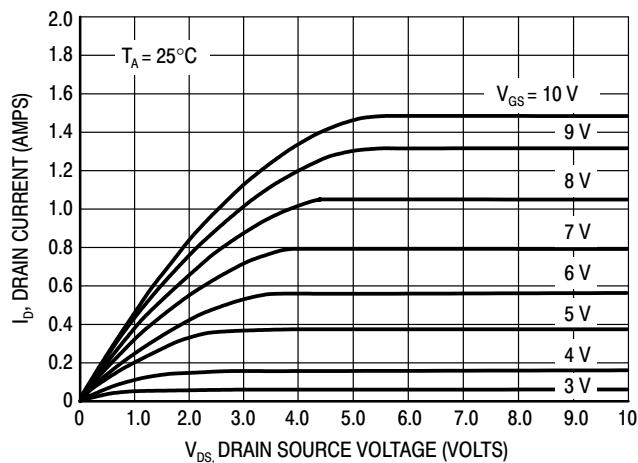


Figure 1. Ohmic Region

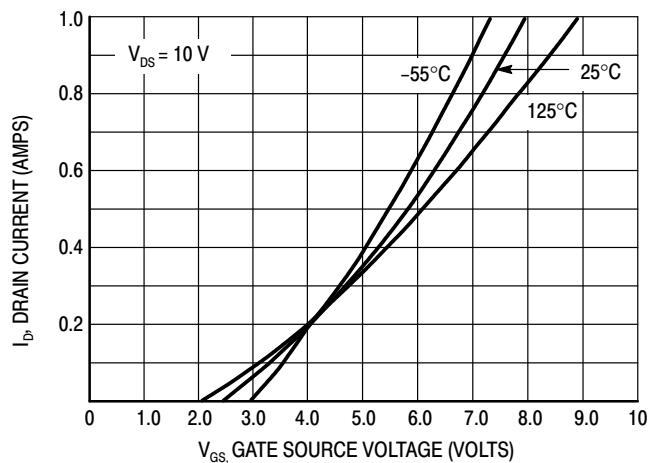


Figure 2. Transfer Characteristics

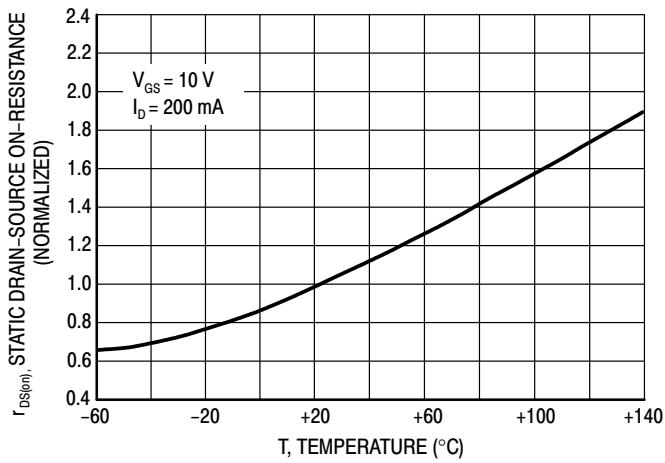


Figure 3. Temperature versus Static Drain-Source On-Resistance

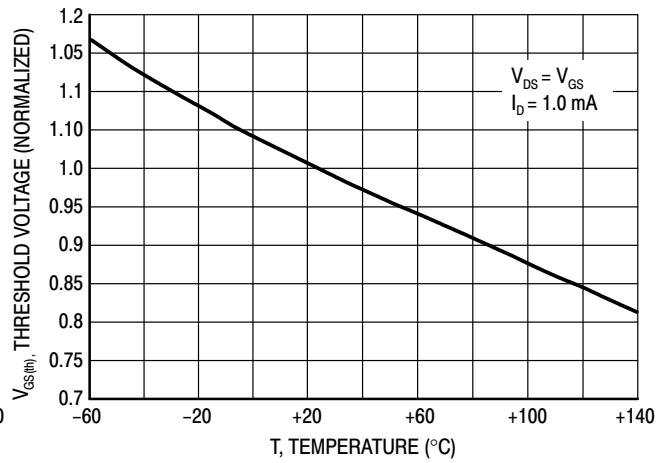


Figure 4. Temperature versus Gate Threshold Voltage